

Product/process change notification

PCN N° 2022-001-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Capacity extension and harmonization of mould compound for dedicated OptiMOS™ products in PG-TDSON-8 package at Tongfu Microelectronics Co. Ltd China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-07-11**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. For further details, please visit our website: <https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Management Board Jochen Hanebeck (CEO), Dr. Helmut Gassel, Constanze Hufenbecher, Dr. Sven Schneider, Dr. Rutger Wijburg

Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

Product/process change notification

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► **Products affected**

Please refer to attached affected product list 1_cip22001_a

► **Detailed change information**

Subject Capacity extension and harmonization of mould compound at Tongfu Microelectronics Co. Ltd. for PG-TDSON-8 package

Reason Expansion of assembly and test production to cover increasing customer demand, and enable flexible manufacturing

Description	<u>Old</u>	<u>New</u>
Assembly and final test location	<ul style="list-style-type: none"> ■ Infineon Technologies Malaysia Sdn. Bhd., Melaka <li style="text-align: center;">and ■ Subcontractor ATX (Weihai) Inc., China <li style="text-align: center;">and ■ Infineon Technologies Wuxi Co., Ltd., China <li style="text-align: center;">and ■ Subcontractor Tongfu Microelectronics Co. Ltd., China (<u>partially</u>)* 	<ul style="list-style-type: none"> ■ Infineon Technologies Malaysia Sdn. Bhd., Melaka <li style="text-align: center;">and ■ Subcontractor ATX (Weihai) Inc., China <li style="text-align: center;">and ■ Infineon Technologies Wuxi Co., Ltd., China <li style="text-align: center;">and ■ Subcontractor Tongfu Microelectronics Co. Ltd., China
Mould Compound	<ul style="list-style-type: none"> ■ Hitachi CEL 1772 <li style="text-align: center;"><i>and</i> ■ Hitachi CEL 9240 	<ul style="list-style-type: none"> ■ Hitachi CEL 9240

* products released already with PCN 2019-001-A

► **Product identification**

Internal traceability via Baunumber, Lotnumber, date code and marking on device and external traceability via marking on device (details 3_cip22001_a)

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► Impact of change

NO change on electrical and thermal performance

NO impact on the device reliability as proven via product qualification and characterization.

NO impact on the electrical parameters and device processability at customer end. Assembly processes are optimized to meet product performance according to already applied Infineon specification

Update of package outline drawing in the datasheet (3_cip22001_a)

► Attachments

1_cip22001_a	affected product list
3_cip22001_a	customer information package

► Time schedule

■ Final qualification report	available
■ First samples available	on request
■ Intended start of delivery	2022-08-01 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local sales office.

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Capacity Extension and Harmonization of Mould compound for Dedicated OptiMOS™ Products in PG-TDSON-8 Package at Tongfu Microelectronics Co. Ltd



Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
BSC007N04LS6	SP001629650	BSC007N04LS6ATMA1	PG-TDSON-8	BSC007N04LS6ATMA1
BSC010N04LS	SP000928282	BSC010N04LSATMA1	PG-TDSON-8	BSC010N04LSATMA1
BSC010NE2LS	SP000776124	BSC010NE2LSATMA1	PG-TDSON-8	BSC010NE2LSATMA1
BSC010NE2LSI	SP000854376	BSC010NE2LSIATMA1	PG-TDSON-8	BSC010NE2LSIATMA1
BSC011N03LS	SP000799082	BSC011N03LSATMA1	PG-TDSON-8	BSC011N03LSATMA1
BSC011N03LSI	SP000884574	BSC011N03LSIATMA1	PG-TDSON-8	BSC011N03LSIATMA1
BSC014N04LS	SP000871196	BSC014N04LSATMA1	PG-TDSON-8	BSC014N04LSATMA1
BSC014N04LSI	SP000953212	BSC014N04LSIATMA1	PG-TDSON-8	BSC014N04LSIATMA1
BSC014N06NS	SP000924886	BSC014N06NSATMA1	PG-TDSON-8	BSC014N06NSATMA1
BSC016N04LS G	SP000394801	BSC016N04LSGATMA1	PG-TDSON-8	BSC016N04LSGATMA1
BSC016N06NS	SP000924882	BSC016N06NSATMA1	PG-TDSON-8	BSC016N06NSATMA1
BSC019N04LS	SP001067012	BSC019N04LSATMA1	PG-TDSON-8	BSC019N04LSATMA1
BSC022N04LS	SP001059844	BSC022N04LSATMA1	PG-TDSON-8	BSC022N04LSATMA1
BSC026N04LS	SP001067014	BSC026N04LSATMA1	PG-TDSON-8	BSC026N04LSATMA1
BSC026N08NS5	SP001154276	BSC026N08NS5ATMA1	PG-TDSON-8	BSC026N08NS5ATMA1
BSC027N06LS5	SP001385616	BSC027N06LS5ATMA1	PG-TDSON-8	BSC027N06LS5ATMA1
BSC028N06NS	SP000917416	BSC028N06NSATMA1	PG-TDSON-8	BSC028N06NSATMA1
BSC030N08NS5	SP001077098	BSC030N08NS5ATMA1	PG-TDSON-8	BSC030N08NS5ATMA1
BSC032N04LS	SP001067018	BSC032N04LSATMA1	PG-TDSON-8	BSC032N04LSATMA1
BSC034N06NS	SP001067010	BSC034N06NSATMA1	PG-TDSON-8	BSC034N06NSATMA1
BSC034N10LS5	SP001385620	BSC034N10LS5ATMA1	PG-TDSON-8	BSC034N10LS5ATMA1
BSC035N10NS5	SP001229628	BSC035N10NS5ATMA1	PG-TDSON-8	BSC035N10NS5ATMA1
BSC036NE7NS3 G	SP000907920	BSC036NE7NS3GATMA1	PG-TDSON-8	BSC036NE7NS3GATMA1
BSC039N06NS	SP000985386	BSC039N06NSATMA1	PG-TDSON-8	BSC039N06NSATMA1
BSC040N10NS5	SP001295030	BSC040N10NS5ATMA1	PG-TDSON-8	BSC040N10NS5ATMA1
BSC050NE2LS	SP000756340	BSC050NE2LSATMA1	PG-TDSON-8	BSC050NE2LSATMA1
BSC066N06NS	SP001067000	BSC066N06NSATMA1	PG-TDSON-8	BSC066N06NSATMA1
BSC0901NS	SP000800248	BSC0901NSATMA1	PG-TDSON-8	BSC0901NSATMA1
BSC0901NSI	SP000819818	BSC0901NSIATMA1	PG-TDSON-8	BSC0901NSIATMA1
BSC0902NS	SP000800246	BSC0902NSATMA1	PG-TDSON-8	BSC0902NSATMA1
BSC0904NSI	SP000854384	BSC0904NSIATMA1	PG-TDSON-8	BSC0904NSIATMA1
BSC0906NS	SP000893360	BSC0906NSATMA1	PG-TDSON-8	BSC0906NSATMA1
BSC093N15NS5	SP001279590	BSC093N15NS5ATMA1	PG-TDSON-8	BSC093N15NS5ATMA1
BSC098N10NS5	SP001241598	BSC098N10NS5ATMA1	PG-TDSON-8	BSC098N10NS5ATMA1
BSC110N15NS5	SP001181418	BSC110N15NS5ATMA1	PG-TDSON-8	BSC110N15NS5ATMA1
BSC117N08NS5	SP001295028	BSC117N08NS5ATMA1	PG-TDSON-8	BSC117N08NS5ATMA1
BSC12DN20NS3 G	SP000781774	BSC12DN20NS3GATMA1	PG-TDSON-8	BSC12DN20NS3GATMA1
BSC160N15NS5	SP001181422	BSC160N15NS5ATMA1	PG-TDSON-8	BSC160N15NS5ATMA1
BSC320N20NS3 G	SP000676410	BSC320N20NS3GATMA1	PG-TDSON-8	BSC320N20NS3GATMA1
BSC350N20NSFD	SP001108124	BSC350N20NSFDATMA1	PG-TDSON-8	BSC350N20NSFDATMA1
BSC500N20NS3 G	SP000998292	BSC500N20NS3GATMA1	PG-TDSON-8	BSC500N20NS3GATMA1
BSC600N25NS3 G	SP000676402	BSC600N25NS3GATMA1	PG-TDSON-8	BSC600N25NS3GATMA1
BSC670N25NSFD	SP001107234	BSC670N25NSFDATMA1	PG-TDSON-8	BSC670N25NSFDATMA1
BSC900N20NS3 G	SP000781780	BSC900N20NS3GATMA1	PG-TDSON-8	BSC900N20NS3GATMA1

**Capacity extension and harmonization of
mould compound for dedicated OptiMOS™
products in PG-TDSON-8 package at
Tongfu Microelectronics Co. Ltd.**

PCN 2022-001-A



- confidential -

Comparison of Marking on Device

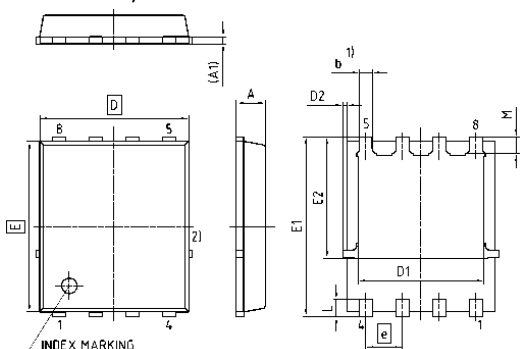
	Old	New
Assembly and final test location	<ul style="list-style-type: none"> Infineon Technologies Malaysia Sdn. Bhd., Melaka Subcontractor ATX (Weihai) Inc., China Infineon Technologies Wuxi Co., Ltd., China Subcontractor Tongfu Microelectronics Co. Ltd., China 	<ul style="list-style-type: none"> Infineon Technologies Malaysia Sdn. Bhd., Melaka Subcontractor ATX (Weihai) Inc., China Infineon Technologies Wuxi Co., Ltd., China Subcontractor Tongfu Microelectronics Co. Ltd., China
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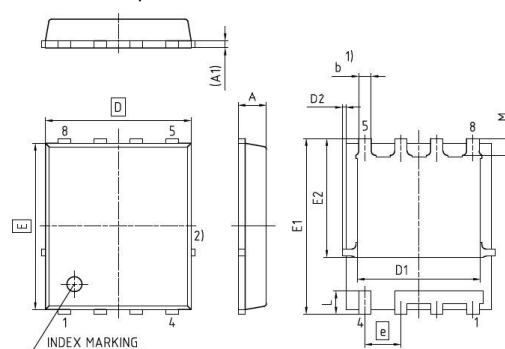
Package Outline Drawing Comparison

SYMBOL	Non fused lead				SYMBOL	Fused lead			
	TDSON-8 (old) [mm]		TDSON-8 (new) [mm]			TDSON-8 (old) [mm]		TDSON-8 (new) [mm]	
	Issue: 11/01/2017 Rev: 06		Issue: 06/06/2019 Rev: 07			Issue: 02/08/2011 Rev: 01		Issue: 19/06/2019 Rev: 03	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	0.90	1.10	0.90	1.20	A	0.90	1.10	0.90	1.20
A1	0.15	0.35	0.15	0.35	A1	0.15	0.35	0.15	0.35
b	0.31	0.54	0.34	0.54	b	0.34	0.54	0.34	0.54
D	4.95	5.35	4.80	5.35	D	4.95	5.35	4.80	5.35
D1	3.70	4.40	3.90	4.40	D1	3.70	4.40	3.70	4.40
D2	0.02	0.22	0.03	0.23	D2	0.02	0.22	0.02	0.23
E	5.70	6.10	5.70	6.10	E	5.90	6.10	5.70	6.10
E1	5.95	6.35	5.90	6.42	E1	6.05	6.25	5.90	6.42
E2	3.81	4.31	3.88	4.31	E2	3.81	4.31	3.88	4.42
e	1.27		1.27		e	1.27		1.27	
L	0.45	0.71	0.45	0.71	L	0.74	0.84	0.69	0.90
M	0.45	0.75	0.45	0.69	M	0.45	0.66	0.45	0.69

TDSON-8, Non fused lead



TDSON-8, Fused lead





Part of your life. Part of tomorrow.